

ABSTRACT OF THE DISCLOSURE

The invention provides an electronic circuit unit that is suitable for miniaturization and excellent in high frequency characteristic. Capacitors and a wiring pattern are formed on an alumina substrate by means of thin film forming technique, and a part of the wiring pattern is served as the connection land for mounting a bare chip of a transistor. Among the capacitors, the top electrode of the capacitor is served also as a part of the connection land, and the bottom side collector electrode of the bare chip is connected to the connection land by use of conductive adhesive. Top electrodes of the residual capacitors are served as the bonding pad, and the base electrode and the emitter electrode on the top side of the bare chip are connected to the top electrodes of the respective capacitors by a wire.